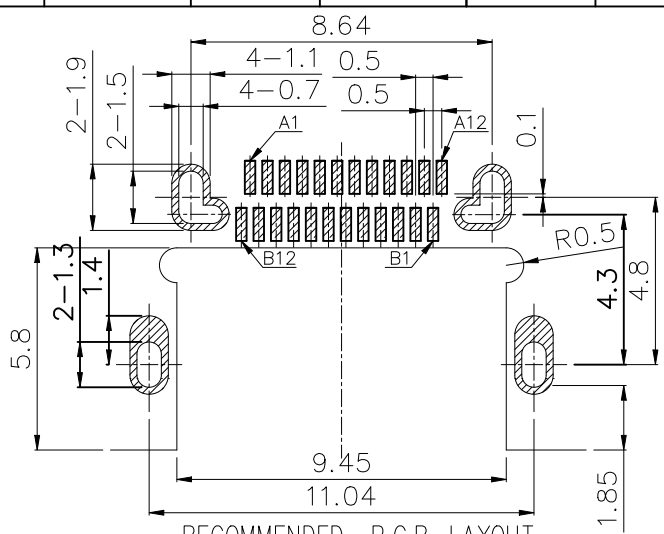
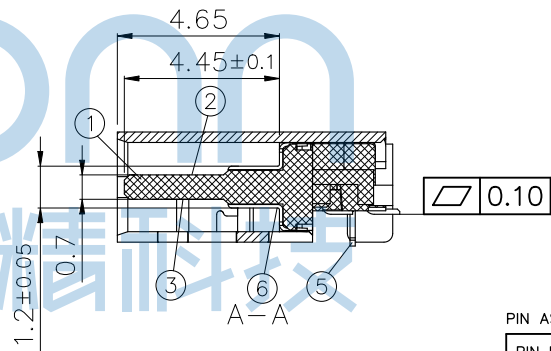
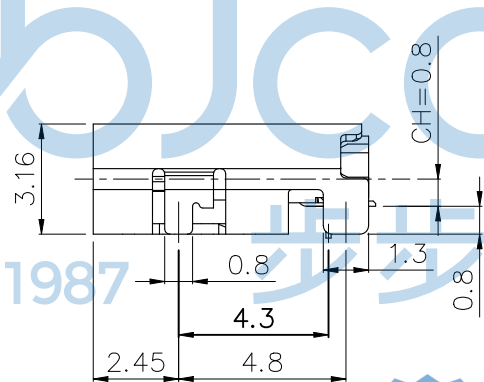
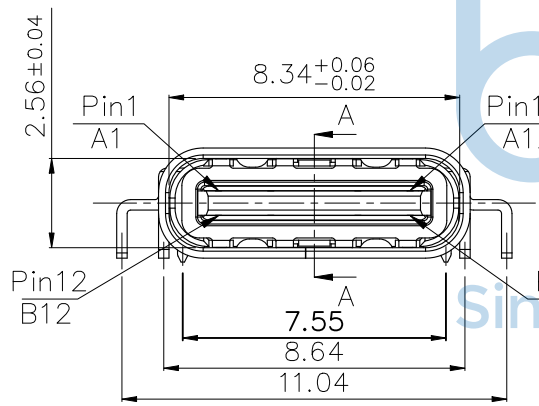
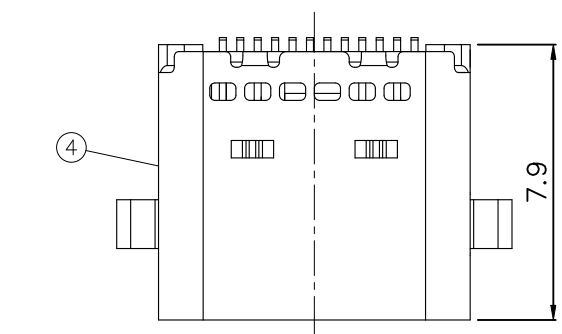


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTES:
 1. MECHANICAL PERFORMANCE,
 1-1. INSERTION FORCE: 5N~20N.
 1-2. REMOVAL FORCE: 5N~20N.
 1-3. DURABILITY: 10000 CYCLES.
 2. ELECTRICAL PERFORMANCE,
 2-1. CURRENT RATING: 5.0A
 2-2. LLCR: VBUS & GND PINS AND OTHER PINS: 40mΩ /PIN MAX. SHIELD: 50mΩ /MAX.
 2-3. INSULATION RESISTANCE: 100MΩ MIN
 2-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
 3. ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -25° C~+85° C.



RECOMMENDED P.C.B. LAYOUT
 TOLERANCE UNSPECIFIED ±0.05mm

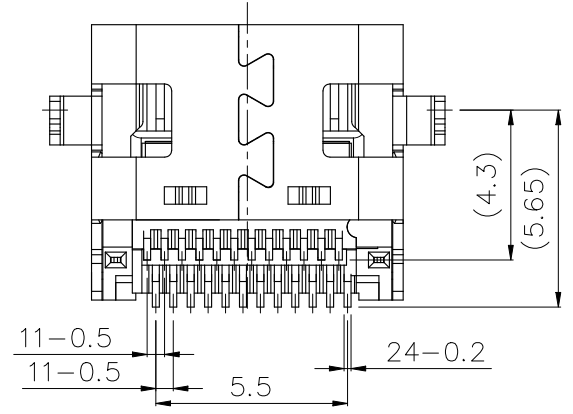
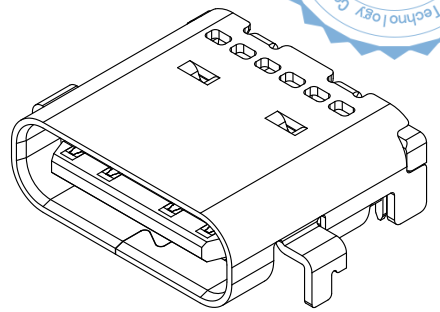


PIN ASSIGNMENTS:

PIN No.	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
SIGNAL NAME	GND	TX1+	TX1-	Vbus	CC1	D+	D-	SBU1	Vbus	RX2-	RX2+	GND
PIN No.	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
SIGNAL NAME	GND	RX1+	RX1-	Vbus	SUB2	D-	D+	CC2	Vbus	TX2-	TX2+	GND



⑥	EMI PLATE	1 PCS	STAINLESS STEEL T=0.10	
⑤	MID PLATE	1 PCS	STAINLESS STEEL T=0.15	Soldering Plating: Sn
④	SHELL	1 PCS	STAINLESS STEEL T=0.3	Ni
③	TERMINAL 2(12Pin)	1SET	COPPER ALLOY T=0.15	Under Plating: Ni Contact Plating: Au 3u"
②	TERMINAL 1(12Pin)	1SET	COPPER ALLOY T=0.15	Soldering Plating: Au
①	HOUSING	1 PCS	HIGH TEMP.THERMOPLASTIC UL94V-0	BLACK
NO.	PART NAME	QTY.	MATERIAL	REMARK



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION. PDWG.NO: 0470-1

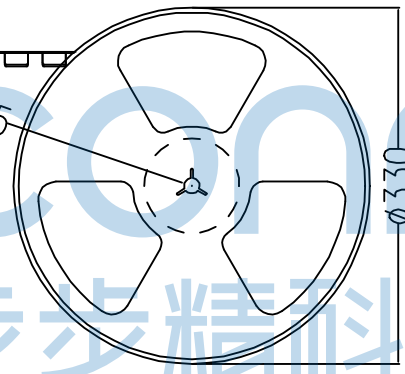
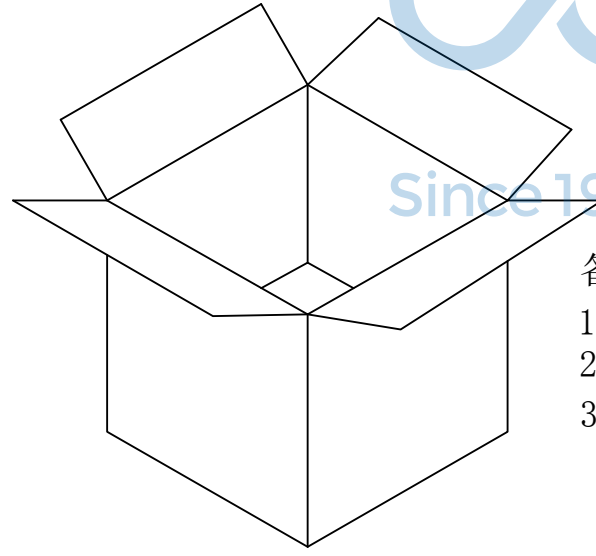
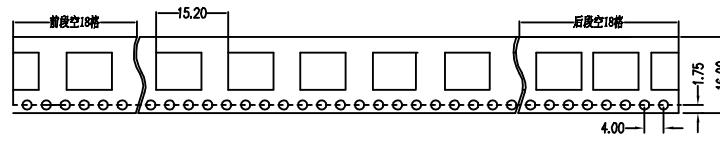
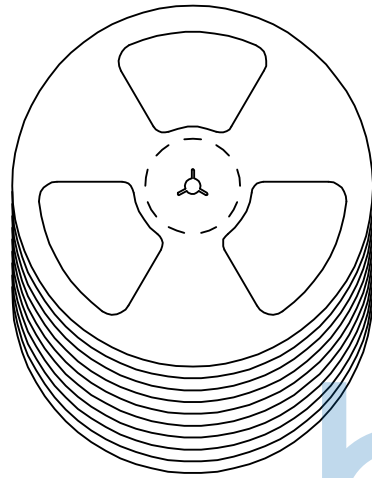
深圳市步步精科技有限公司

NAME: TYPE-C 24P 母座 L=7.90 CH=0.80 沉板0.8 端子镀金3u 双排SMT 带EMI 外壳镀黑镍

PJ. NO.: 126-221-240028-U4G
 SIZE: A4 DRW NO.:
 FINISH: SEE NOTES MAT'L.: SEE NOTES
 SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2

APPD. JM_Zheng
 CHKD. LYX
 DR. TSP

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



备注:

1. 包装数量: 900/PCS/卷, 10卷/箱。
2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
3. 材质:
载体: 聚丙烯 (PS),
上带: 聚乙烯 (PET),
卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM

THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司	
.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X': ±3" X'': ±2" X'X': ±1"	
APPD.	JM_Zheng	NAME: TYPE-C 24P 母座 L=7.90 CH=0.80 沉板0.8 端子镀金3u 双排SMT 带EMI 外壳镀黑镍	
CHKD.	LYX	PJ. NO.: 126-221-240028-U4G	
DR.	TSP	SIZE: A4 DRW NO.:	
PDWG.NO: 0470-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2	